AMENDMENTS TO THE CLAIMS

This listing of the claims will replace all prior versions and listing of the claims in this application.

LISTING OF THE CLAIMS:

1. (Withdrawn) A multiple force tool for applying pressure to circuit board components comprising:

first, second and third support channels for supporting first, second and third horizontally extending arms over a circuit board having multiple components;

a plurality of pressure cylinders supported by said horizontally extending arms over each of said components; and

means connected to said pressure cylinders for extending a pressure foot of said cylinders to a position for applying a bonding force against said components providing pressure contact between board components and said circuit board.

2. (Withdrawn) The multiple force tool according to claim 1 wherein said horizontally extending arms are positionable along said channels to vary the location of said pressure cylinders along a first axis.

3. (Withdrawn) The multiple force tool according to claim 1 wherein said horizontally extending arms include means for positioning said pressure cylinders along a second axis.

4. (Withdrawn) The multiple force tool according to claim 2 wherein said channels include position indicia for establishing a position coordinate for said pressure cylinders along said first axis.

Claims 5-10 (Canceled)

11. (Currently amended) A method for applying a bonding pressure to circuit board components being bonded to a circuit board comprising:

supporting first, second and third pressure cylinders over the components on said circuit board along one of first and second axes, each of said pressure cylinders having a foot which extends under air pressure against said components; and

supplying a source of pressurized air simultaneously to said pressure cylinders whereby feet of said pressure cylinders simultaneously ~~extends~~ extend to apply a force against said components for a duration of time sufficient to bond an adhesive coated component to said circuit board.

12. (Previously presented) The method for applying pressure to said pressure cylinders according to claim 11 wherein said step of supporting includes a step of positioning said pressure cylinders along said first and second axes to align said cylinder feet with a respective component on said circuit board.

13. (Previously presented) The method for applying a pressure to said pressure cylinders according to claim 12 wherein said positioning step includes positioning arms for supporting said pressure cylinder along channels which are located along said axes.

14. (Previously presented) The method according to claim 11 wherein said pressurized air is supplied as a timed pulse wherein said pressure is applied to said components for a fixed duration of time.

15. (Previously presented) The method according to claim 11 wherein said step of supplying said timed pulse of pressurized air includes regulating the time pulse of air.